

November 2013

FQP19N20

N-Channel QFET[®] MOSFET 200 V, 19.4 A, 150 m Ω

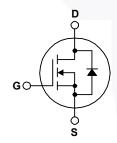
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 19.4 A, 200 V, $R_{DS(on)}$ = 150 m Ω (Max.) @ V_{GS} = 10 V, I_D = 9.7 A
- Low Gate Charge (Typ. 31 nC)
- Low Crss (Typ. 30 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP19N20	Unit
V _{DSS}	Drain-Source Voltage		200	V
I _D	Drain Current - Continuous (T _C = 25°C	C)	19.4	Α
	- Continuous (T _C = 100	°C)	12.3	А
I _{DM}	Drain Current - Pulsed	(Note 1)	78	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	250	mJ
I _{AR}	Avalanche Current	(Note 1)	19.4	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	14	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P_D	Power Dissipation (T _C = 25°C)		140	W
	- Derate above 25°C		1.12	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FQP19N20	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.89	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP19N20	FQP19N20	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.18		V/°C
I _{DSS}	lpss - C	V _{DS} = 200 V, V _{GS} = 0 V			1	μΑ
Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C			10	μΑ	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 9.7 A	\	0.12	0.15	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 9.7 A		14.5		S
C _{iss}	ic Characteristics Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		1220	1600	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		220		•
	Output Oapacitarice					
C_{rss}	Reverse Transfer Capacitance			30	290 40	•
Switch	ing Characteristics			30	40	•
Switch	ing Characteristics Turn-On Delay Time	V _{DD} = 100 V, I _D = 19.4 A,		30	40	pF
Switch t _{d(on)} t _r	ing Characteristics Turn-On Delay Time Turn-On Rise Time	$V_{DD} = 100 \text{ V}, I_{D} = 19.4 \text{ A},$ $R_{G} = 25 \Omega$		30 20 190	50 390	pF ns
Switch t _{d(on)} t _r t _{d(off)}	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time	$R_G = 25 \Omega$		20 190 55	50 390 120	ns ns
Switch t _{d(on)} t _r t _{d(off)} t _f	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	R_G = 25 Ω (Note 4)	 	30 20 190 55 80	50 390 120 170	pF ns ns ns
Switch td(on) tr td(off) td	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	R_G = 25 Ω (Note 4) V_{DS} = 160 V, I_D = 19.4 A,	 	20 190 55 80 31	50 390 120 170 40	ns ns ns ns
Switch t _{d(on)} t _r t _{d(off)} t _f Q _g Q _{gs}	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge	$R_G = 25 \Omega$ (Note 4) $V_{DS} = 160 \text{ V}, I_D = 19.4 \text{ A}, V_{GS} = 10 \text{ V}$	 	30 20 190 55 80 31 8.6	50 390 120 170 40	ns ns ns ns
Switch t _{d(on)} t _r t _{d(off)} t _f Q _g Q _{gs}	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	R_G = 25 Ω (Note 4) V_{DS} = 160 V, I_D = 19.4 A,	 	20 190 55 80 31	50 390 120 170 40	ns ns ns ns
Switch t _{d(on)} t _r t _{d(off)} t _f Q _g Q _{gs} Q _{gd}	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge	R_G = 25 Ω (Note 4) V_{DS} = 160 V, I_D = 19.4 A, V_{GS} = 10 V (Note 4)	 	30 20 190 55 80 31 8.6	50 390 120 170 40	ns ns ns ns
$t_{d(on)}$ t_r $t_{d(off)}$ t_f Q_g Q_{gs} Q_{gd}	ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_{G} = 25 \Omega \label{eq:RG}$ (Note 4) $V_{DS} = 160 \text{V}, I_{D} = 19.4 \text{A}, \ V_{GS} = 10 \text{V} \ \text{(Note 4)}$ and Maximum Ratings	 	30 20 190 55 80 31 8.6	50 390 120 170 40	ns ns ns ns

Q_{rr}

 t_{rr}

 V_{SD}

Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 1.0 mH, I_{AS} = 19.4 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C. 3. I_{SD} \leq 19.4 A, di/dt \leq 300 A/µs, V_{DD} \leq BV_{DSS}, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Drain-Source Diode Forward Voltage

Reverse Recovery Time

Reverse Recovery Charge

1.5

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140

0.69

V

ns

μС

 $V_{GS} = 0 \text{ V}, I_{S} = 19.4 \text{ A}$

V_{GS} = 0 V, I_S = 19.4 A,

 $dI_F / dt = 100 A/\mu s$

Typical Characteristics

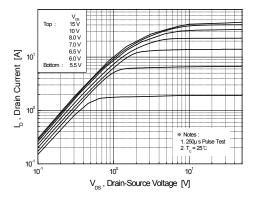


Figure 1. On-Region Characteristics

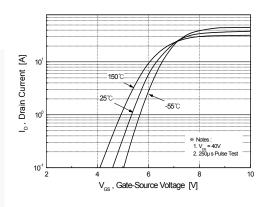


Figure 2. Transfer Characteristics

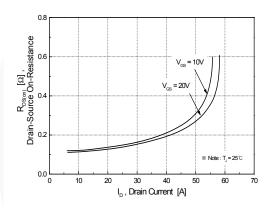


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

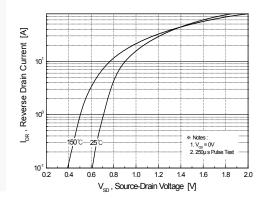


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

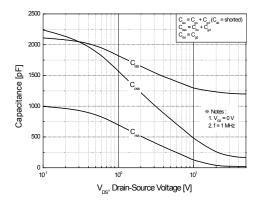


Figure 5. Capacitance Characteristics

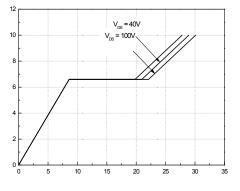


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

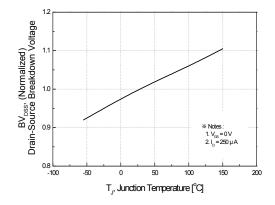
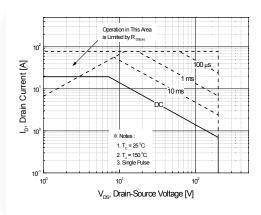


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



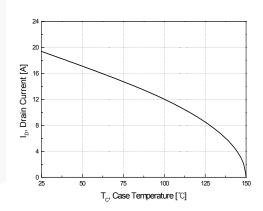


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

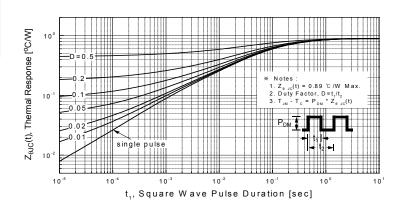


Figure 11. Transient Thermal Response Curve

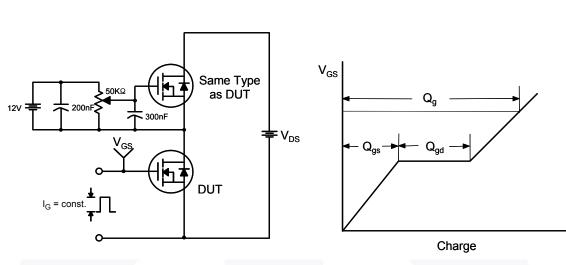


Figure 12. Gate Charge Test Circuit & Waveform

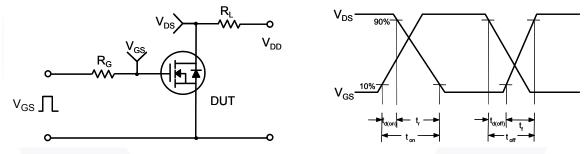


Figure 13. Resistive Switching Test Circuit & Waveforms

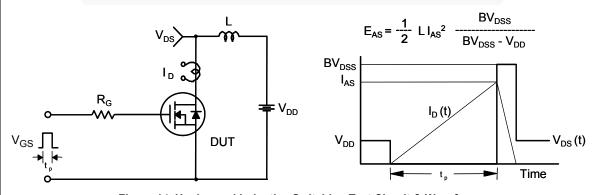
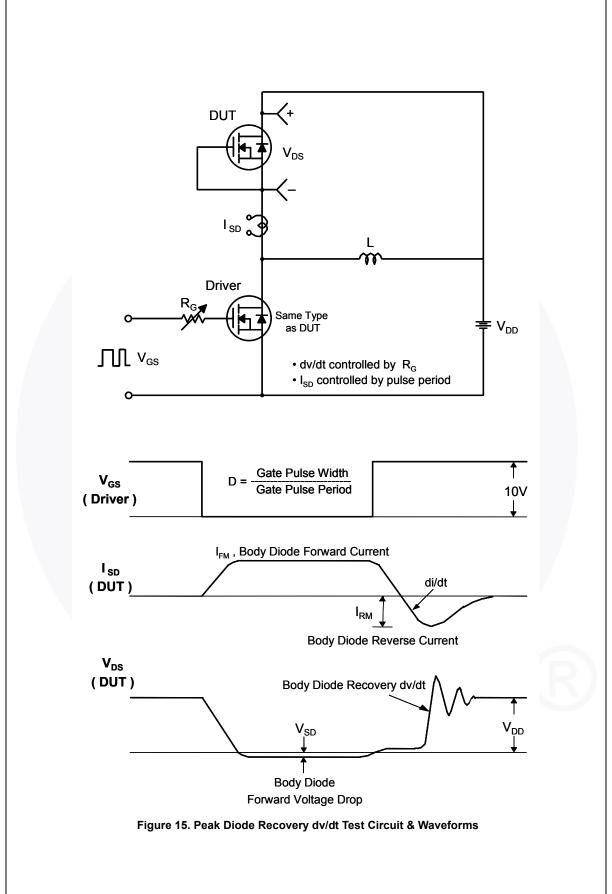
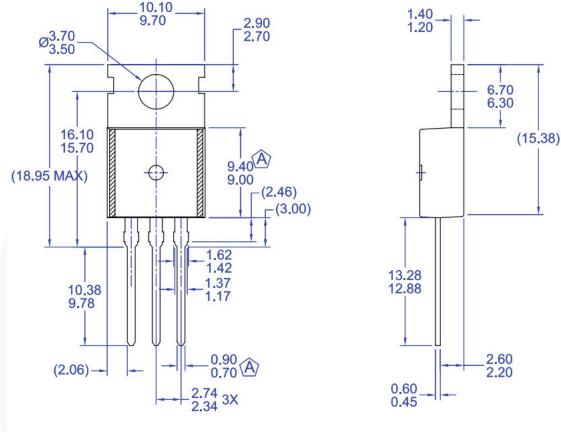
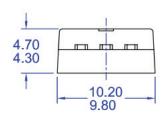


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions





NOTES:

- (A) CONFORMS TO JEDEC TO-220 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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